

SEMICON WEST TECHNOLOGY BREAKFAST

July 11, 2023 at 7:00 AM PT

Yerba Buena Center for the Arts, San Francisco



MARK FUSELIER

Senior Vice President

Technology and Product Engineering

AMD

Mark Fuselier is senior vice president of Technology and Product Engineering at AMD. He is responsible for silicon and packaging technology development and product engineering.

Mark has more than 27 years of semiconductor industry experience and has been involved in the development and production of process technology generations spanning from 0.35 μ m through 4nm across multiple fabs and product families. He has played a central role in the development and productization of computing solutions such as multi-core CPU and GPU SoC integration, heterogeneous APUs, 2.5D and 3D chip packaging, and chiplet System-in-Package (SiP) integration.

Mark holds a Master of Science degree in electrical engineering and Master of Business Administration from the University of Texas at Austin. He is a member of IEEE and the Electron Devices Society.

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BABAK SABI

Senior Vice President

General Manager

Intel Corporation

Dr. Babak Sabi is a Senior Vice President and the General Manager of Assembly & Test Technology Development (ATTD) at Intel Corporation. Since 2009, he has been responsible for the company's packaging, assembly and test process technology development.

Babak joined Intel in 1984. Prior to leading ATTD, he oversaw Intel's Corporate Quality Network from 2002 to 2009 where he led product reliability, customer satisfaction and quality business practices.

Babak received his Ph.D. in solid state electronics from Ohio State University in 1984. He has authored ten papers on reliability physics and has received five Intel Achievement Awards. He currently holds two patents.

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PR “CHIDI” CHIDAMBARAM

Vice President

Engineering

Qualcomm

PR. Chidi Chidambaram leads the process technology engineering team at Qualcomm as Vice President of Engineering and is recognized as Qualcomm Fellow.

Qualcomm is a leader in the fabless industry – introducing leading-edge semiconductor technologies to manufacturing. Qualcomm was the first company to ship large volume products in 10nm technology in 2017. In addition to the leading-edge CMOS technologies, Chidi’s team is also responsible for RF devices based on FinFET and SOI transistors.

Before joining Qualcomm, Chidi developed silicon technology at Texas Instruments and was instrumental in the first embedded SiGe implementation by the semiconductor industry. He is also recognized by IEEE as a fellow for his contribution to strain engineering and design technology co-optimization (DTCO). In his 20+ year semiconductor career, evenly distributed between research and development, Chidi has written and earned over 100 referred articles and patents each.

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RICHARD BLICKMAN

President

CEO

BE Semiconductor Industries N.V.

Richard Blickman started his career at ASMI in February 1984 and initiated BE Semiconductor Industries N.V. on October 1, 1993 through a buyout of a packaging equipment company from ASMI supported by a German-based equity investor. Shortly thereafter a Dutch plating equipment company was added followed by an IPO in 1995.

The strategy from day one has been to focus on the forefront of advanced packaging, allowing ever more miniaturization of semiconductor device generations for leaders in communication devices, high-end computing and automotive. Since 2000, Besi broadened its scope upstream to die attach through four acquisitions in the US, Austria and Switzerland. Operations have been established in Malaysia, China and support from Singapore. Besi has a total workforce of 1,800. Richard has served as CEO since the company's initiation in 1993.

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PAUL LINDNER

*Executive Technology Director
EV Group*

Paul Lindner is EV Group's executive technology director. He heads the R&D, product and project management, quality management, business development and process technology departments. Customer orientation throughout all steps of product development, innovation and implementation in a production environment are among the main goals of EV Group's technology groups headed by Paul.

Paul joined the company in 1988 as a mechanical design engineer and has since pioneered various semiconductor and MEMS processing systems, which have set industry standards. His responsibilities included the design of semiconductor processing systems and tooling for custom applications, including innovative system designs pioneered in the first commercially available wafer bonders, silicon-on-insulator (SOI) bonding systems and precision alignment systems for 3D interconnect applications. Prior to his appointment as executive technology director, Paul established a product management department at EV Group. During that time he was involved in marketing, sales, manufacturing and on-site process support.

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PRABU RAJA

President

Semiconductor Products Group

Applied Materials Fellow

Applied Materials, Inc.

Dr. Prabu Raja is president of the Semiconductor Products Group (SPG) at Applied Materials where he leads semiconductor process equipment businesses and the global field organization. Under his leadership, SPG has delivered substantial growth and is in a very strong position for the future. Since its formation, the group has expanded Applied's portfolio of co-optimized and integrated solutions to address customers' most complex and valuable problems and established the company's leadership at key inflections.

Prabu is regarded as a trusted partner by customers and has charted a remarkable career at Applied. Having joined the company as a process engineer in 1995, he demonstrated his gifts and skills as an innovator in PVD and helped secure Applied's leadership position in Metals. Over the years he led the development of many winning products, including Ionized Metal Plasma Ti/TiN and the family of Encore Tantalum and Copper products (CuBS).

In 2010, he was recognized as an Applied Fellow for his outstanding technical contributions. He also brought his drive and passion to reinvigorate the company's Etch business, which included introducing Sym3—the fastest ramping product in Applied's history. He was also instrumental in developing Applied's advanced packaging strategy, building critical ecosystem partnerships, and creating the Applied Packaging Development Center lab in Singapore.

Prabu holds a Ph.D. in plasma physics from the Indian Institute of Technology, Delhi and continued his research at the University of Iowa. He has numerous patents and publications.

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SUNDAR RAMAMURTHY

Group Vice President

General Manager

Semiconductor Products Group

Applied Materials, Inc.

Dr. Sundar Ramamurthy is responsible for Applied's business in wafer-level packaging, specialty semiconductors and epitaxy markets. In this role, Sundar leads an integrated team across the company to fuel growth in some of the fastest growing markets in the semiconductor industry.

Over the past two decades, Sundar and his team have delivered profitable growth for the corporation in multiple areas of semiconductor equipment technologies – rapid thermal processing, plasma doping, physical vapor deposition, atomic layer and chemical vapor deposition of thin metal films. He led teams that commercialized 20+ new products to solve critical transistor and interconnect scaling challenges by introducing new materials and interface engineering solutions into volume manufacturing.

Sundar holds a Ph.D. in materials science and engineering from the University of Minnesota. He has more than 30 patents granted or pending. Sundar is also an active mentor with the Miller Center in Santa Clara University for accelerating social enterprises.

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MIKE RICE

*Corporate Vice President
Semiconductor Products Group
Applied Materials Fellow
Applied Materials, Inc.*

Mike Rice is Corporate Vice President of Engineering in the Semiconductor Products Group at Applied Materials. He is responsible for leading and developing core competencies and product solutions to support company growth and partnering with suppliers to deliver high-quality products. In July 2011, he was awarded the honorary designation of Applied Materials Fellow for his outstanding technical contributions that have been vital to the company's success.

Mike joined Applied Materials in 1992 as an engineering manager in dielectric etch and has served in roles with increasing responsibility across etch and foundation engineering, most recently as general manager of foundation engineering. His broad capability and wealth of engineering experience has been invaluable in the development and performance of common and automation subsystems used across all of the company's product lines. Before joining Applied Materials, he led new product development for Silicon Valley Group's photolithography track division.

Mike earned a bachelor of science degree in mechanical engineering from California Polytechnic State University in San Luis Obispo. He holds more than 180 patents in plasma etching, ALD products, robotics, mainframes and platform architectures.

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VINCENT DICAPRIO

Vice President
Semiconductor Products Group
Applied Materials, Inc.

Vincent DiCaprio has over 33 years of experience in technology development, operations, business, and sales and marketing, having demonstrated success at companies including IBM, Amkor, ASE, TSMC and GLOBALFOUNDRIES. He joined Applied Materials in 2016.

Currently leading corporate and business development for the Advanced Packaging and ICAPS groups at Applied Materials, Vincent is responsible for forging new strategic alliances and partnerships key to technology advancement for future product solutions. He leads all aspects of critical technology inflections related to heterogenous integration, next-generation integration of silicon, and volumetric scaling for all key aspects of the technology stack related to advanced packaging and 3D ICs.

Vincent holds a degree in pure and applied sciences from Champlain Regional College, and a bachelor of engineering degree from Concordia University. He is both the author and co-author of more than 30 patents in the field of advanced semiconductor packaging.

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MICHAEL SULLIVAN

Corporate Vice President

Investor Relations

Applied Materials, Inc.

Michael Sullivan is Corporate Vice President and head of Investor Relations. His team is responsible for investor relations and marketing communications including media relations, product and technology communications, and industry events.

Michael joined Applied in 2009 after working at Intel Corporation for 16 years. He was Intel's primary interface to equity analysts and the company's largest institutional shareholders in the U.S. and Europe. He also held corporate communications positions at the company's U.S. and European offices, where he drove corporate and competitive initiatives, new microprocessor introductions, computing platform campaigns and flash memory PR.

Michael is past president of the Silicon Valley chapter of NIRI, the National Investor Relations Institute. He earned his MBA at Santa Clara University and his BA in public relations at San Jose State University.